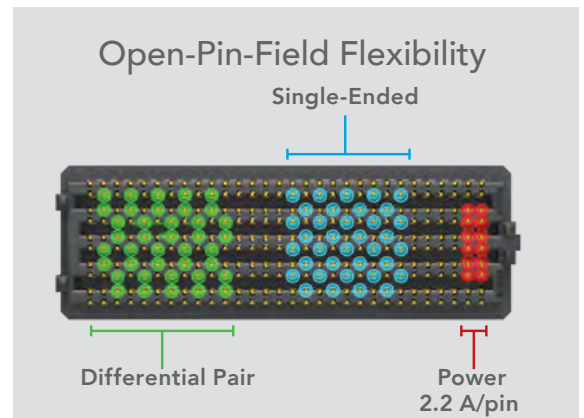




LOW PROFILE OPEN-PIN-FIELD ARRAYS

LP ARRAY™ HIGH-SPEED/HIGH-DENSITY SYSTEMS

- Low profile stack heights: 4 mm, 4.5 mm and 5 mm
- .050" (1.27 mm) pitch for maximum grounding and routing flexibility
- Up to 50 pins per row
- 4, 6 or 8 row configurations
- Dual beam contact system
- Solder crimped termination for ease of processing
- Board stacking standoffs available to assist unmating and reduce risk for component damage on boards



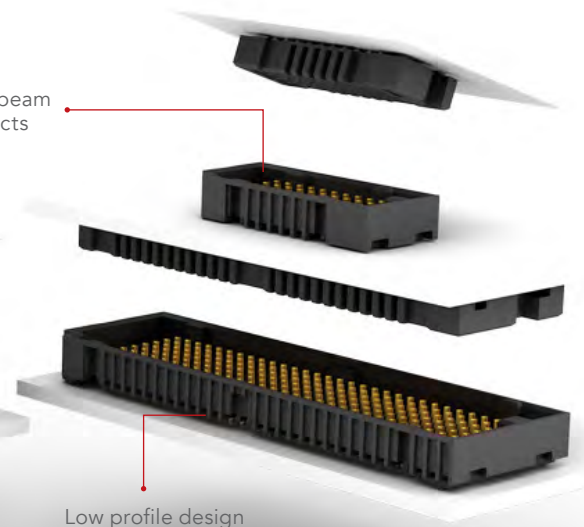
LPARRAY™

PAM4
56
G b p s



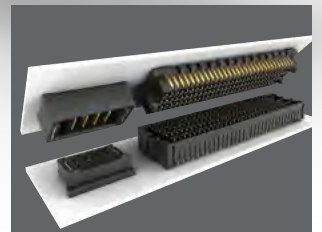
Press-in or threaded
stand offs

Dual beam
contacts



Low profile design

LP Array™ is compatible with
UMPT/UMPS for flexible two-
piece power/signal solutions.



System

- **LPAM** – .050" Pitch Array Terminal
- **LPAF** – .050" Pitch Array Socket
- **JSO** – Jack Screw Precision Board Stacking Standoff

For more High-Speed/High-Density Solutions, please visit samtec.com/arrays